



Using resonant soft X-ray scattering to image patterns on undeveloped resists

Guillaume Freychet, I. Cordova, D. Kumar, T. McAfee, C. Anderson, P. Naulleau, C. Wang and Alexander Hexemer

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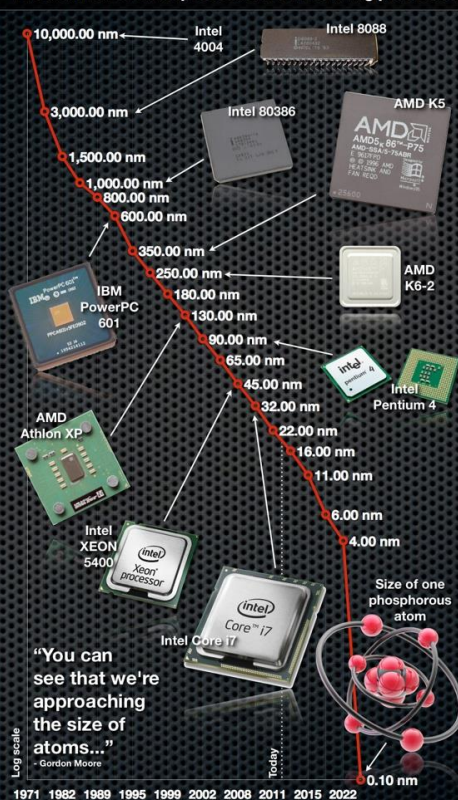
U.S. DEPARTMENT OF
ENERGY

Office of
Science



How small can a transistor be?

The evolution of microprocessor manufacturing processes



Data source: Wikipedia
Graphics from Intel, Shutterstock, and Wikipedia

www.pingdom.com

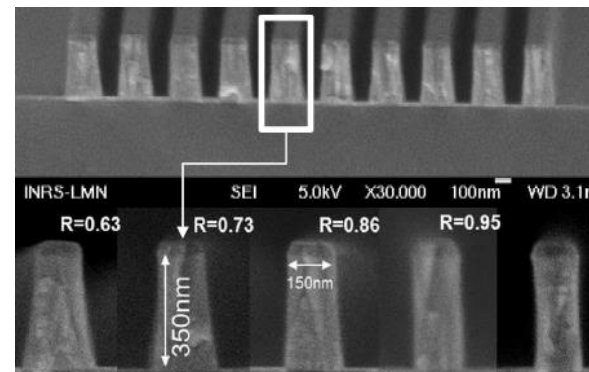
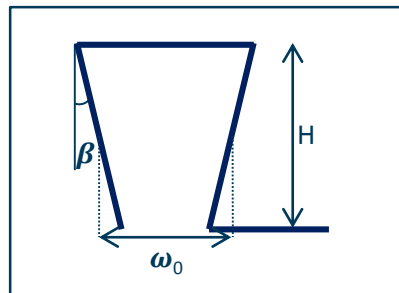
Context for the semi-conductor industry

Parameters to control :

- ✓ Pitch
- ✓ Linewidth
- ✓ Line height
- ✓ Roughness
- ✓ Sidewall angle

Sub-nm
resolution

1D array : Line gratings

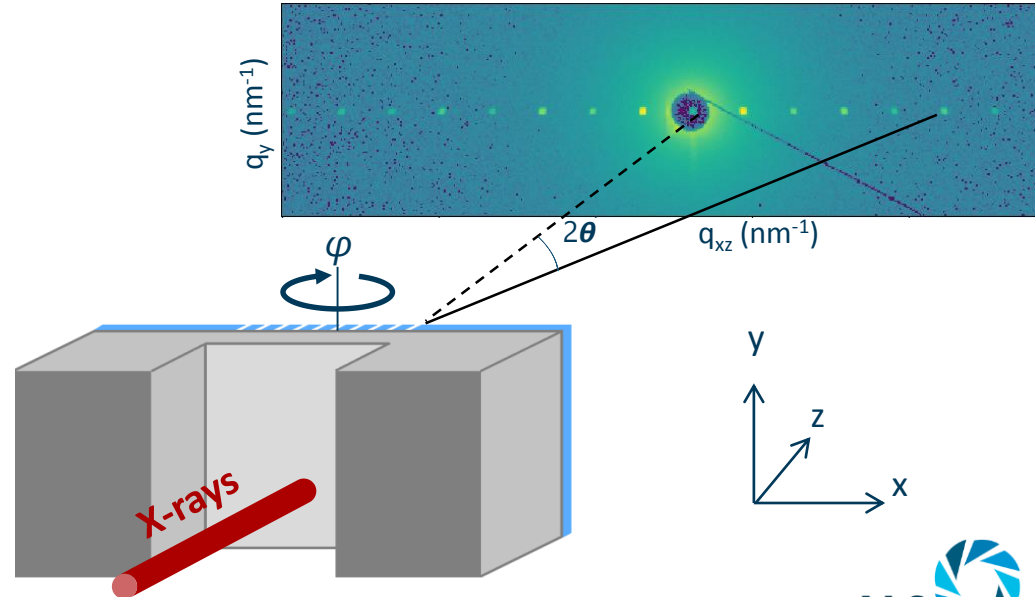
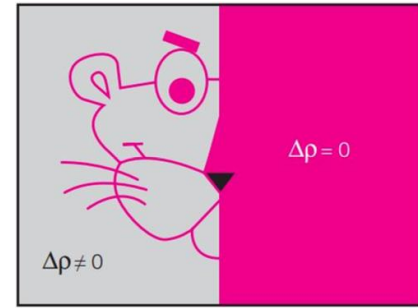


With the size reduction of the objects,
any sub-nm defects will impact strongly
the performance of the device

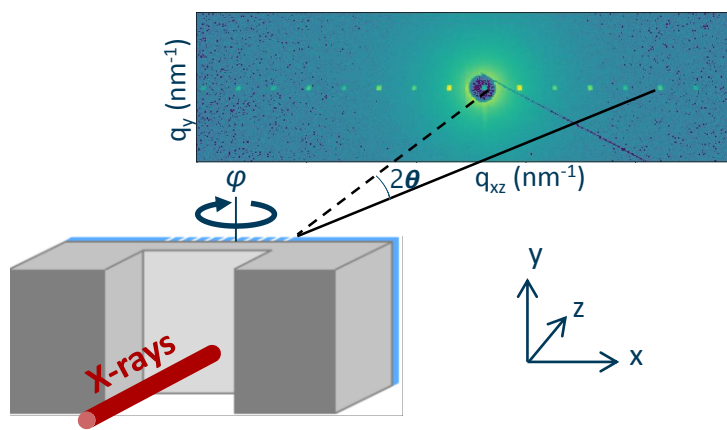
Small Angle X-ray Scattering (SAXS)

- ✓ Probe electronic density contrast
- ✓ Small angle scattering: probe 1-1000 nm

$$q = \frac{2\rho}{l} \sin 2\theta$$



Small Angle x-ray scattering (SAXS) on line gratings

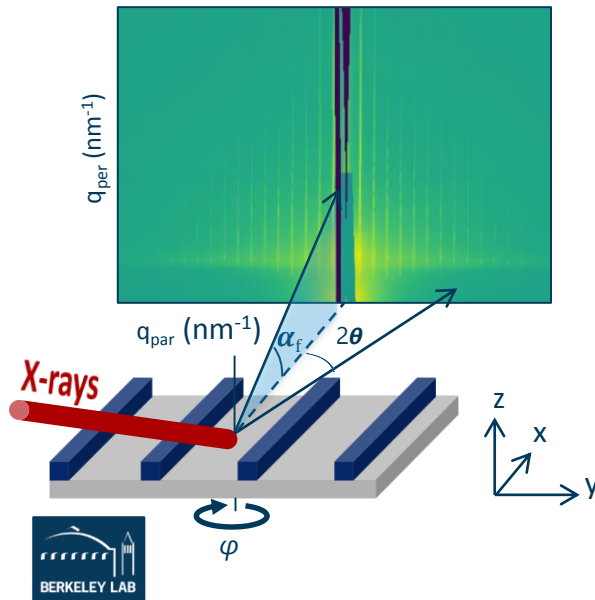


- ✓ Transmission configuration
- ✓ High energy x-ray source

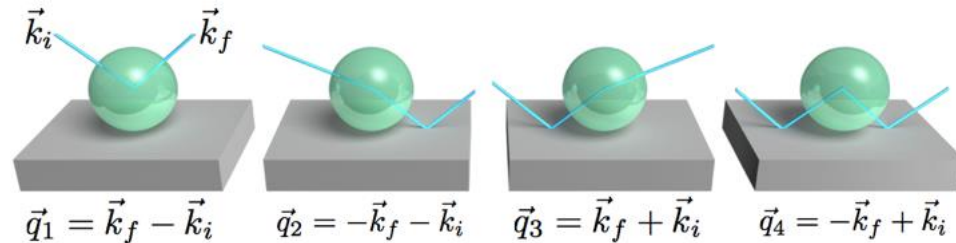
D. F. Sunday et al., ACS Appl. Mater. Interfaces (2017)

Grazing-incidence SAXS (GISAXS)

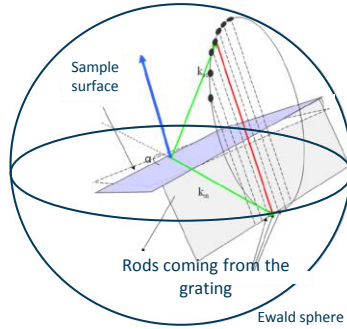
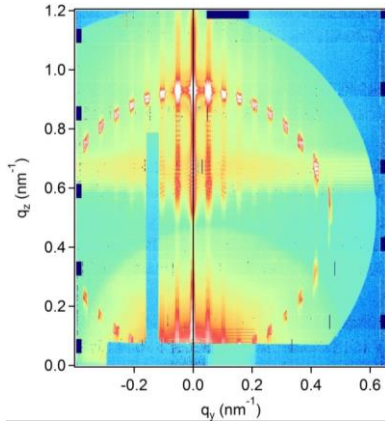
- ✓ Small incidence angle < 0.2 deg
- ✓ Probe thin films on **Silicon wafer (700 μm)**



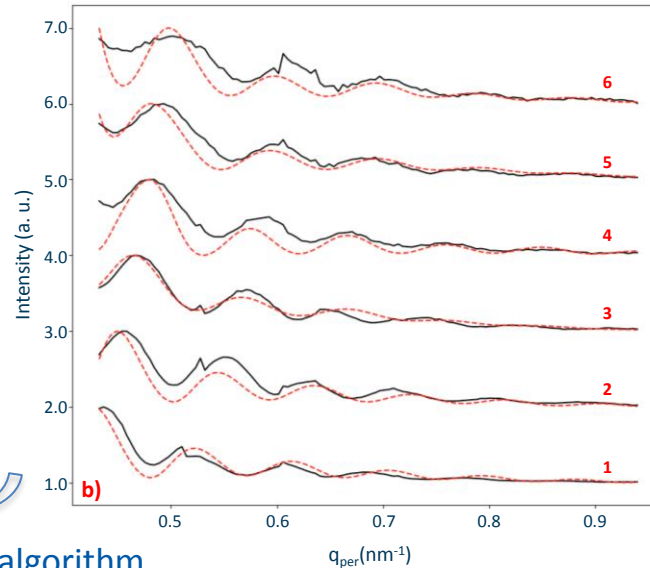
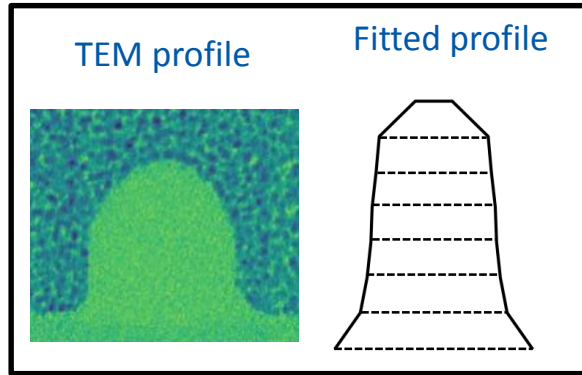
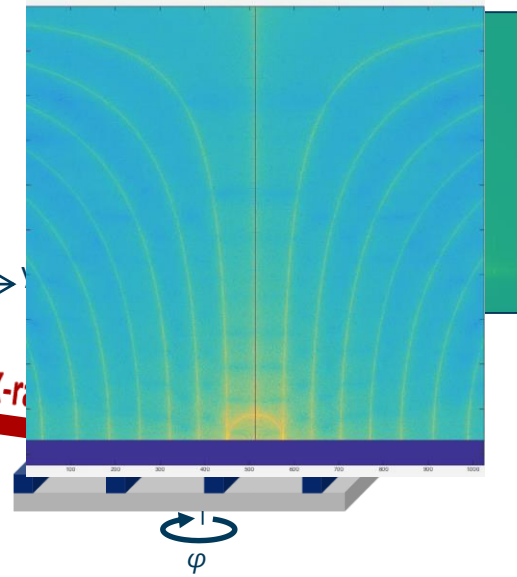
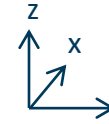
Distorted Wave Born Approximation



Critical-Dimension GISAXS



Rotation of the gratings
(along z)



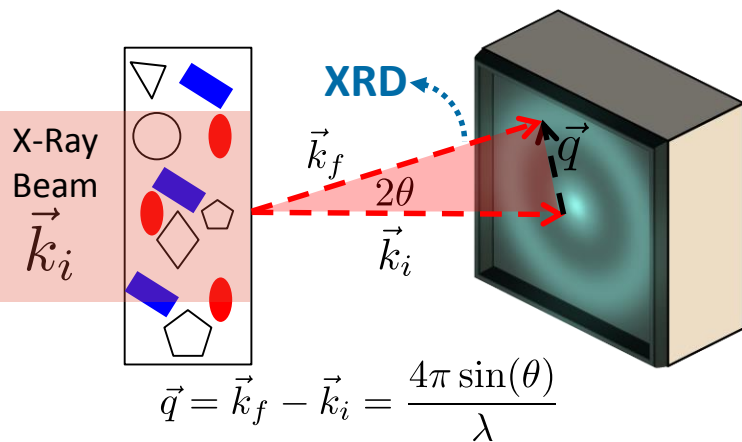
1D vertical
cut

Fit using genetic algorithm

Resonant Soft X-Ray Scattering (RSoXS)

Reconstruction of a latent image (before removal of the exposed resist)

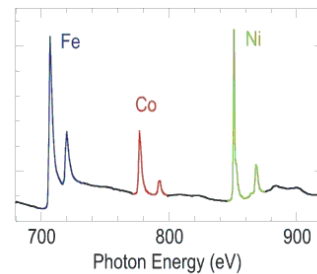
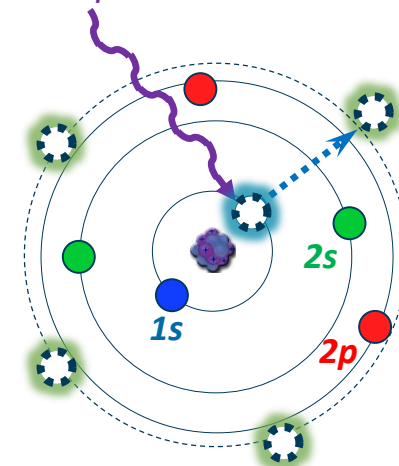
Small Angle X-Ray Scattering



Credit: Guinnier A. *et al*, *Ann Phys*, **1939**, 12:161–237

X-Ray Absorption

Tunable photon



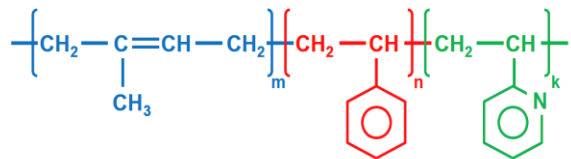
Credit: Wanli Yang, ALS

Electronic density:

$$|\delta^2 + \beta^2|$$

RSoXS applications

Triblock copolymer:



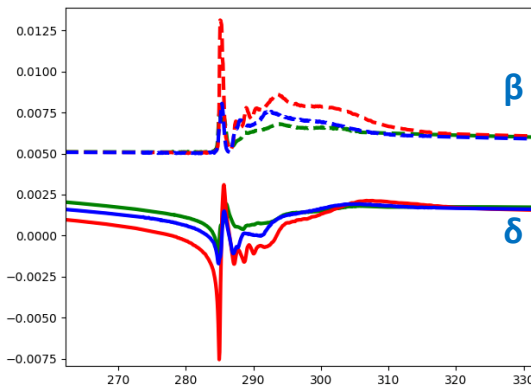
$M_{n,PI} = 9,000\text{g/mol}$

$M_{n,PS} = 60,000\text{g/mol}$

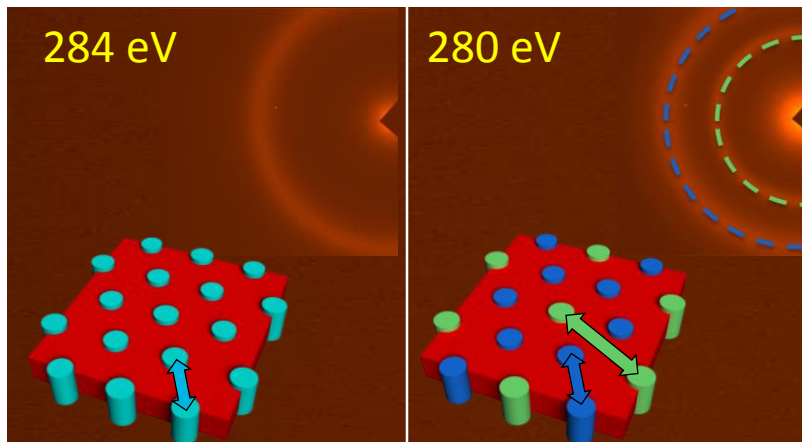
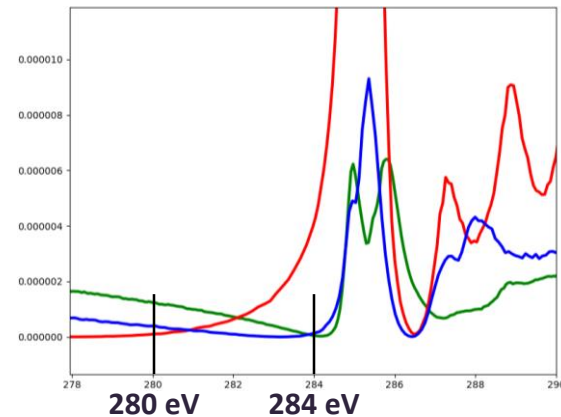
$M_{n,P2VP} = 11,000\text{g/mol}$

- ✓ Tune the energy to enhance the scattering contrast
- ✓ Before the absorption edge to reduce beam damage

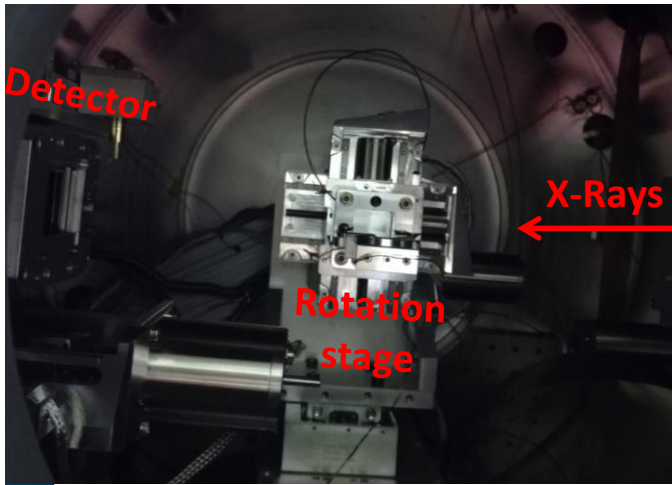
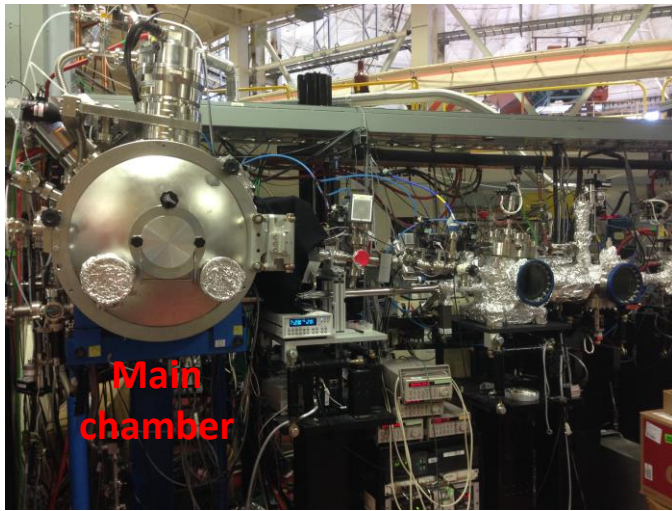
Credit: C. Wang *et al*, *Nano Lett.*, **2011**, 11, 3906



Electronic density $|\delta^2 + \beta^2|$



11.0.1.2 Beamline at the ALS



CD-GIRSOXS of latent image

Chain-scission EUV resist:

- ✓ E-beam exposition
- ✓ 200 nm pitch line gratings
- ✓ Post-Exposure baking

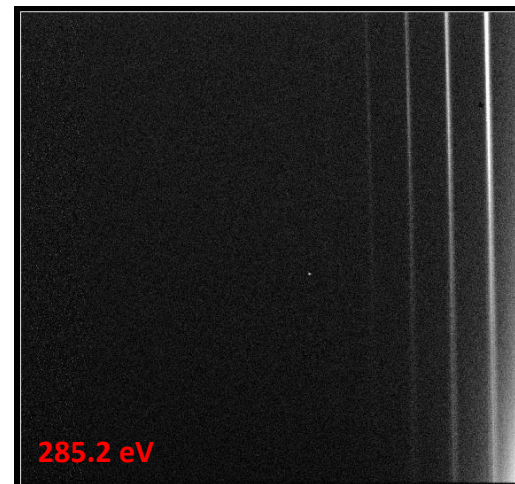
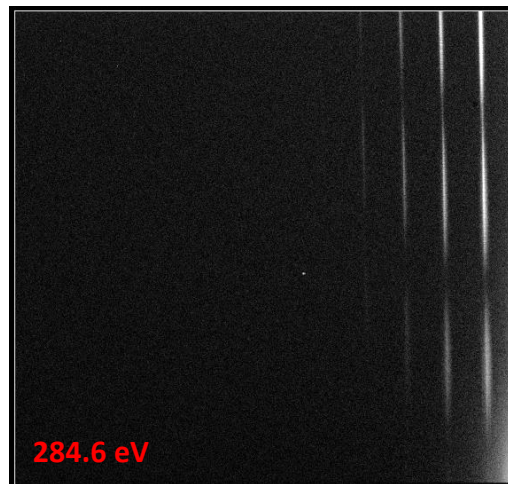
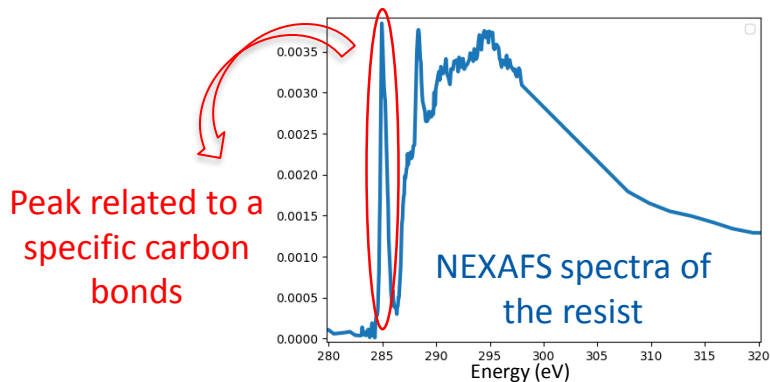


Exposition + bake:
Chain scission

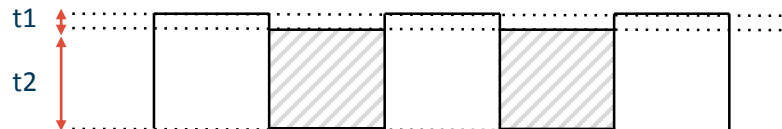
Modification of the carbon environment

Modification of the β and δ

Introduction of a scattering contrast



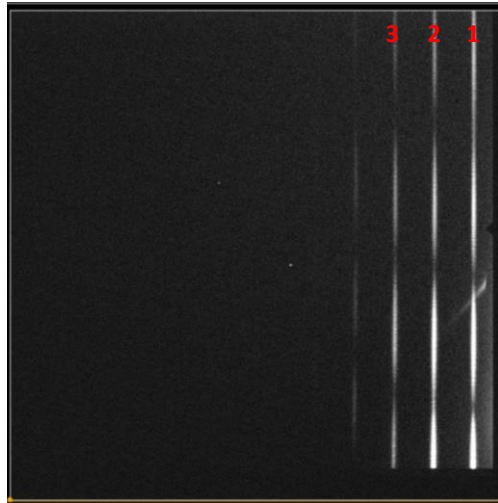
- ✓ **284.6 eV: Electronic density contrast**
- ✓ **285.2 eV: No electronic density contrast**



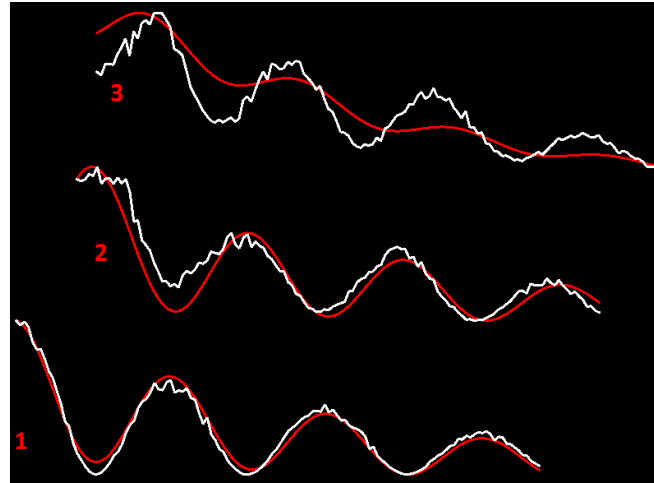
Contrast between exposed/unexposed resist at 284.6 eV

CD-GISAXS of latent image using Resonant scattering

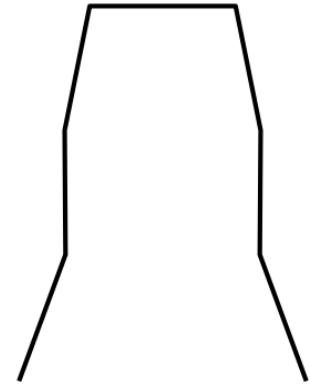
Reconstruction of the 3D shape of a latent image



1D vertical cut



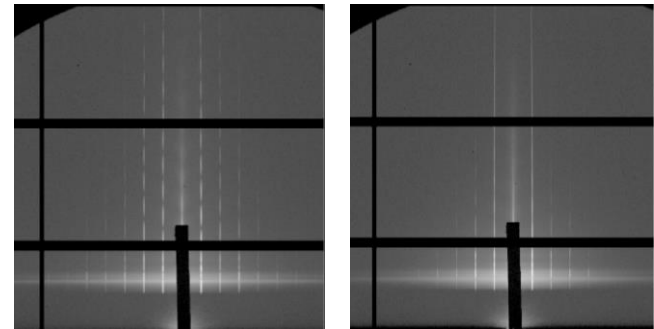
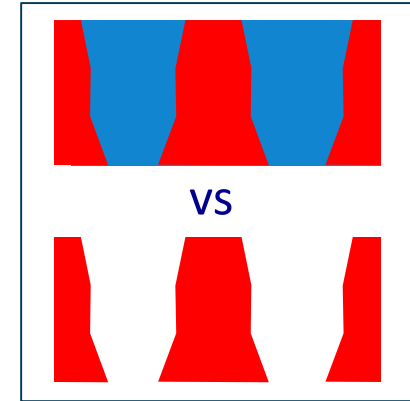
Extracted profile



- ✓ New perspectives to control the 3D shape of a latent image
- ✓ Short measurement time: 10 seconds
- ✓ Beam damage?

Conclusion

- ✓ 3D reconstruction of the latent image with a sub-nm resolution
- ✓ Trapezoidal shape after the exposition
- ✓ Comparison before and after development
- ✓ Test on different resists (different elements edges)
- ✓ Quantification of the roughness
- ✓ Study beam damage on the sample



FEM wafer (IMEC)

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Weilun Chao
Christopher Anderson



Daniel Staaks
Scott Dhuev
Peter Ercius



**Thank you for your
attention!**



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